

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MICRON.110A	APPLICATION NO. 09/471,071
O I P E INFORMATION DISCLOSURE STATEMENT BY APPLICANT  AUG 21 2000 (USE SEVERAL SHEETS IF NECESSARY)		APPLICANT Tongbi Jiang	
		FILING DATE December 21, 1999	GROUP 2835

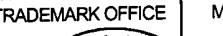
U.S. PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
JHA	5,045,921	09/03/91	Lin et al.			
JHA	5,216,278	06/01/93	Lin et al.			*
JHA	5,659,952	08/26/97	Kovac et al.			
JHA	5,821,609	10/13/98	DiStefano et al.			
JHA	5,879,965	03/09/99	Jiang et al.			

FOREIGN PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
						YES      NO

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)	
[REDACTED]		

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EXAMINER	[Signature]	DATE CONSIDERED	11/28/01
*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.			

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## **U.S. PATENT DOCUMENTS**

## **FOREIGN PATENT DOCUMENTS**

**EXAMINER INITIALS** \_\_\_\_\_ **OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)**

JHA	"Area Tape Automated Bonding Ball Grid Array Technology" by Chin-Ching Huang and Ahmad Hamzehdoost, Ball Grid Array Technology, Chapter 14, pgs. 443-464 (1995)
JHA	"Face-down BGA shrinks memory products by 75%", by Spencer Chin, Outlook
JHA	"Tessera's Micro-Ball Grid Array (μBGA)", Chapter 16, pgs. 259-282
JHA	"Advanced Encapsulant Systems for Flip-Chip-on-Board Assemblies: Underfills with Improved manufacturing Properties" by Daniel R. Gamota and Cindy M. Melton, IEEE Transactions on Components, Packaging, and Manufacturing Technology - Part C, Vol. 21, No. 3, July 1998

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EXAMINER	<i>Joseph A. Alcaide</i>	DATE CONSIDERED	11/28/01
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